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Part Number: [0736442018](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location N/A, Polarizing Key Position N/A, 72 Circuits, Mating Length 5.00mm

Documents:

3D Model	Packaging Specification PK-70873-0818 (PDF)
3D Model (PDF)	RoHS Certificate of Compliance (PDF)
Drawing (PDF)	

Agency Certification

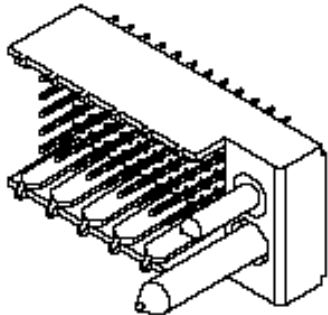
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit, Tin/Lead (SnPb), Standard Press-Fit, Tin/Lead (SnPb)
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754852012

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



Series image - Reference only

EU ELV

Not Reviewed

EU RoHS

Not Reviewed

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

For more information, please visit [Contact US](#)

China RoHS

China ROHS	Not Reviewed
ELV	Not Reviewed
RoHS Phthalates	Not Reviewed

Search Parts in this Series

[73644](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard Receptacle. [73780](#) HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SDA-73644-XXXX

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